

## Product Bulletin Document #:PB21821XA

Document #:PB21821XA Issue Date: 22 August 2017

Title of Change:	Improved SOT5X3 cross bar of carrier tape at ON Semiconductor, Leshan, China factory.	
Effective date:	22 August 2017	
Contact information:	Contact your local ON Semiconductor Sales Office or < <a href="mailto:coleen.Long@onsemi.com">coleen.Long@onsemi.com</a> >	
Type of notification:	ON Semiconductor will consider this change accepted.	
Change category:	☐ Wafer Fab Change ☐ Assembly Change	☐ Test Change ☐ Other <u>Cross Bar of Carrier Tape Change</u>
Change Sub-Category(s):  Manufacturing Site Change Manufacturing Process Cha		<ul><li>□ Datasheet/Product Doc change</li><li>☑ Shipping/Packaging/Marking</li><li>□ Other:</li></ul>
Sites Affected: ☐ All site(s) ☐ not a	pplicable	☐ External Foundry/Subcon site(s)
Description and Purpose:		
Improved SOT5X3 cross bar of carrier tape to eliminate potential risk of unit rotate in tape. All new product releases currently incorporate this type of carrier tape and products listed in this product bulletin are being converted after the proposed ship date.		
The MPQ, reel size and cover tape dimension have no changes. There does not require any modifications to the assembly processes or flows.		
There is no change to the form, fit, or function of the physical part.		
List of Affected Standard Parts:		
EMC5DXV5T1G NSBC114EPDXV6T1G		

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